

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5025	382/149,145,224,159,100,141,155,181.CQLS.	USPAT	OR	ON	2009/06/29 11:58
L2	4478	715/774,835,837,764,841,210,839,762,809,804,973,250,866,708.CQLS.	USPAT	OR	ON	2009/06/29 12:01
L3	1453	719/310,315.CQLS.	USPAT	OR	ON	2009/06/29 12:01
L4	355	714/E11.21.CQLS.	USPAT	OR	ON	2009/06/29 12:02
L5	1846	356/237.1,237.2.CQLS.	USPAT	OR	ON	2009/06/29 12:03
L6	834	702/35,1,33.CQLS.	USPAT	OR	ON	2009/06/29 12:04
L7	599018	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:29
L8	125	L7 and user adj select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:32
L9	3	L8 and input adj user and page and learning adj mode and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:34
L10	4	L8 and input and user and page and learning adj mode and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:37
L11	4	L8 and learning adj mode and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:55

L12	1	L8 and automatic adj defect and recognition and(detect\$3 or determining)/and(defect or flaw or fault)/and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:58
L13	11	automatic adj defect and recognition and(detect\$3 or determining)/and(defect or flaw or fault)/and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
L14	10	L13 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
L15	1	L14 and user adj select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
L16	1	L14 and user adj select\$3 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
L17	3	automatic adj defect and recognition and(detect\$3 or determining)/and(defect or flaw or fault)/and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and (illumination or source or light or optimal adj intensity or light adj intensity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:12
L18	3	automatic adj defect and recognition and(detect\$3 or determining)/and(defect or flaw or fault)/and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:16
L19	0	L18 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:17
L21	781	L1 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:19
L22	3	L21 and user adj select\$3 and review and data adj file	USPAT	OR	ON	2009/06/29 13:19

L23	27	L21 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:20
L24	0	L23 and input and user and page and learning adj mode and parameters	USPAT	OR	ON	2009/06/29 13:21
L26	0	L23 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:23
L27	0	L23 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:24
L28	2	L23 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:25
L29	2	L28 and(@ad<"20030712" or @rad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 13:28
L30	0	L28 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:32
L31	0	L28 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:43
L32	0	L28 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)and(detected\$3 or determining)and(defect or flaw or fault)	USPAT	OR	ON	2009/06/29 13:46
L33	18	L2 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:48
L34	4	L33 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:48
L35	0	L34 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:48
L36	0	L34 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:52
L37	2	L3 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:53
L38	0	L37 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:55

L39	0	L37 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:56
L40	0	L37 and select\$3 adj(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:56
L41	2	L3 and(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)	USPAT	OR	ON	2009/06/29 13:59
L42	1	L4 and(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)	USPAT	OR	ON	2009/06/29 13:59
L43	0	L42 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:59
L44	0	L42 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:59
L45	0	L42 and select\$3 adj(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:00
L46	733	L5 and(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)	USPAT	OR	ON	2009/06/29 14:01
L47	5	L46 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:01
L48	0	L47 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:01
L49	0	L47 and select\$3 adj(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:01
L50	5	L47 and(@ad<"20030712" or @lad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 14:02
L51	0	L47 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:03
L52	599018	(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L53	83	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04

L54	19	L53 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L55	12	L54 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L56	3	L55 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L57	685554	L56 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L58	18	L53 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L59	17	L58 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L60	2	L52 and L53 and L57 and L59	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
L61	0	L60 and @ad<"20030712"	USPAT	OR	ON	2009/06/29 14:04
L63	129	L6 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 14:06
L64	4	L63 and user adj select\$3 and review and (storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:06
L65	0	L64 and select\$3 adj (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (capturing or pictures or cod or camera) and align\$4 and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:07

L66	0	L64 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:08
L67	3	L64 and(@ad<"20030712" or @lad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 14:09
L68	0	L67 and select\$3 adj(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:23
L69	1	L63 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:26
L70	0	L69 and select\$3 adj(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:26
L71	0	L69 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:28
L74	0	(knowledge adj based adj database and automatic adj defect adj classificat\$3 and selectinf adj review adj data and input adj parameters and learning adj mode and alignment and adjusting adj intensity and optimal adj intensity and descriptors adj defects).CLM.	US-PGPUB	OR	ON	2009/06/29 14:41
L75	0	(knowledge adj based adj database and automatic adj defect adj classificat\$3 and selecting adj review adj data and input adj parameters and learning adj mode and alignment and adjusting adj intensity and optimal adj intensity and descriptors adj defects).CLM.	US-PGPUB	OR	ON	2009/06/29 14:41
L76	0	(knowledge adj based and database and automatic adj defect adj classificat\$3 and selecting and review adj data and input adj parameters and learning adj mode and alignment and adjusting adj intensity and optimal adj intensity and checking adj detection and optimization and pictures and assigned and descriptors adj defects).CLM.	US-PGPUB	OR	ON	2009/06/29 14:45
L77	0	(knowledge adj based and database and automatic adj defect adj classificat\$3 and selecting adj review adj data and parameters and learning adj mode and alignment and adjusting adj intensity and optimal adj intensity and checking adj detection and optimization and pictures and assigned and descriptors adj defects).CLM.	US-PGPUB	OR	ON	2009/06/29 14:46
L78	0	(knowledge adj based and database and automatic adj defect adj classificat\$3 and selecting adj review and data and parameters and learning adj mode and alignment and adjusting adj intensity and optimal adj intensity and checking adj detection and optimization and pictures and assigned and descriptors adj defects).CLM.	US-PGPUB	OR	ON	2009/06/29 14:46
L79	1	((wafer\$1 or semiconductor\$ or chip\$ or substrat\$1) and user adj select\$3 and review and data adj file and input and user and page and learning adj mode).clm.	US-PGPUB	OR	ON	2009/06/29 14:51
S1	571947	(wafer\$1 or semiconductor\$ or chip\$ or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:27

S2	1	S1 and automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:29
S3	1	automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S4	1	S1 and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S5	1	defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S6	2	defect adj classification and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S7	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S8	19	S7 and (water\$1 or semiconductor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S9	17	S8 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
S10	12	S8 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36

S11	24	((DIRK) near2 (SOENKSEN)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:36
S12	11	((RALF) near2 (FRIEDRICH)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S13	1	((ANDREAS) near2 (DRAEGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S14	2	((DETLEF) near2 (SCHUPP)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S16	2	((THIN) near2 (~VAN LUU)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
S17	3	((WOLFGANG) near2 (LANGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
S18	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S19	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S20	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S21	0	S12 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S22	0	S13 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:43
S23	3	S10 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:46

S24	638382	S23 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:47
S25	0	S23 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:47
S26	18	S7 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:48
S27	0	S26 and parameters and learning adj node	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:49
S28	0	S26 and parameters and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:49
S29	17	S26 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:49
S30	2	S1 and S7 and S24 and S29	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:56
S31	2	S30 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:56
S32	18	S7 and S26	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 11:57

S33	16	S32 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:58
S34	20	S1 and automatic and defect adj recognition	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:00
S35	638382	S34 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:01
S36	4	S34 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:33
S37	1	S34 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S38	0	S37 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S39	16	S34 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S40	0	S39 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S41	2	S39 and learning	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35

S42	16	S26 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:39
S43	0	S42 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S44	0	S42 and learning near mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S45	0	S42 and learning near3 mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S46	11	S42 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S47	598	S1 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:44
S48	340	S47 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:44
S49	1	S48 and input and user and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:45
S50	1	S48 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:46

S51	4	S48 and alignment adj procedure	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:46
S52	0	S8 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
S53	0	S48 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
S54	1	automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
S55	11	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S56	5	S55 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S57	1	S56 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S58	0	S57 and edit adj recipe	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05
S59	0	S57 and edit	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05

S60	0	S67 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:07
S61	1	S67 and circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:07
S62	0	S61 and logic adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:08
S63	0	S61 and blank adj wafer\$1	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:08
S64	1	S66 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 14:02
S65	571947	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/06 11:12
S66	2	S65 and select\$3 and review adj data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/06 11:13
S67	2	S65 and review adj data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/06 11:13
S68	638	S65 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/06 11:14

S69	134	S65 and review same data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
S70	0	S69 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S71	0	S69 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S72	1	S69 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S73	11	S68 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S74	5	S73 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S75	5	S74 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S76	1	S75 and (user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
S77	1	S75 and (user or operator or human)and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17

S78	9	S68 and (detect\$3 or determining) and (defect or fault or flaw) and classification and knowledge near3 database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:19
S79	13	learning and (knowledge-based or knowledge adj based) and database and automatic and defect adj classification	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S80	10	S79 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S81	0	S80 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S82	1	S80 and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:22
S83	8	S80 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S84	8	S83 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S85	6	S84 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:43
S86	5	S84 and descriptor adj (defect or fault or flaw)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:46

S87	573639	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:04
S88	19	S87 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:05
S89	640949	S88 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:05
S90	2	S88 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:05
S91	8	S87 and display adj thumbnails	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:07
S92	2	S91 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:07
S93	0	S92 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:15
S94	8	S91 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:27
S95	1	S94 and automatic adj defect and recognition and (detect\$3 or determining) and (defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:29

S96	2	S92 and display adj thumbnails	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30
S97	2	S96 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30
S98	0	S97 and circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:31
S99	0	S97 and defect and (classification or classifier or classify)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:32
S100	0	S97 and(classification or classifier or classify or grouping)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:33
S101	0	S97 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:33
S102	2	S97 and (intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
S103	2	S102 and(illumination or source or light)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
S104	2	S103 and(blank adj wafer\$1 or wafer\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:36

S105	2	S104 and (polymer or layer or oxide adj layer or contact or metal)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:38
S106	0	S105 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:39
S107	0	S105 and focus	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:39
S108	0	S105 and magnificat\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
S109	2	S105 and @ack<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
S110	2	S109 and select\$3 adj recipe	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:41
S111	2	"6973209".pn.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
S112	0	S111 and alignment	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
S113	1	S111 and algn\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40

S114	0	S111 and align\$3 same light	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:41
S115	1	S111 and align\$3 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:41
S116	1	S115 and adjusting	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S117	0	S116 and optimal adj intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S118	1	S116 and optimal	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S119	0	S118 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S120	1	S118 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:43
S121	1	S120 and algorithm	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:46
S122	1	S121 and automatic	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:47

S123	0	S122 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47
S124	1	S122 and (intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47
S125	0	S124 and text adj image\$1	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:48
S126	0	S124 and text	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:48
S127	1	S124 and recipe	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S128	0	S127 and review	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S129	1	S127 and dictionary	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S130	1	S129 and registered	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:50
S131	1	S130 and drag	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:51

S132	82	defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S133	18	S132 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S134	16	S133 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S135	0	S132 and select\$3 same review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
S136	5	S132 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
S137	3	S136 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:14
S138	1	S137 and descriptors	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:19
S139	0	S137 and defect adj descriptors	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:20
S140	82	defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44

SI41	5	SI40 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44
SI42	3	SI41 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44
SI43	2	SI42 and(wafer\$1 or semicondutor\$1 or chip\$1 or subtrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:45
SI44	3	"6408219".pn.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:46
SI45	1	SI44 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:47
SI46	1	SI44 and select\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:48
SI47	732	select\$3 same review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI48	62	SI47 and(wafer\$1 or semicondutor\$1 or chip\$1 or subtrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI49	0	SI48 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50

SI50	0	SI48 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:50
SI51	14	SI48 and @ack<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:51
SI52	0	SI51 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:51
SI53	0	SI51 and display and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:52
SI54	0	SI51 and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:52
SI55	0	SI51 and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 12:12
SI56	0	SI51 and select\$3 adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 12:13
SI57	1	SI51 and align\$3 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 12:13
SI58	0	SI57 and(user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 12:16

SI59	0	SI57 and descriptors	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
SI60	0	SI57 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:36
SI61	11	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
SI62	5	SI61 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
SI63	1	SI62 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
SI64	0	SI63 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
SI65	575216	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
SI66	10	SI65 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59
SI67	643423	SI66 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59

SI68	1	SI66 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00
SI69	0	SI68 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00
SI70	1	SI66 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00
SI71	0	SI70 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:01
SI72	4	SI66 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:01
SI73	0	SI72 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:01
SI74	7745	SI65 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:01
SI75	2341	SI74 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:01
SI76	775	SI75 and logic adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:02

S177	9	S176 and blank adj wafer	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02
S178	8	S177 and @ad< "20030712"	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
S179	0	S178 and resist	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
S180	0	S178 and photo adj resist	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
S181	0	S178 and polymer adj layer	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S182	51765	polymer adj layer	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S183	33269	S182 and @ad< "20030712"	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S184	2388	S183 and oxide adj layer	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
S185	1703	S184 and contact	US-PGPRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05

SI86	16332	SI83 and contact	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
SI87	10	SI86 and metal adj later	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
SI88	1	SI87 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
SI89	1	SI88 and @ack<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
SI90	1	SI89 and(intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
SI91	0	SI90 and align\$3 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
SI92	1	SI90 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
SI93	0	SI92 and magnificat\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
SI94	0	SI92 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08

S195	0	S192 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
S196	0	S195 and focus\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:12
S197	51832	polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S198	33269	S197 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S199	16332	S198 and contact	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S200	10	S199 and metal adj later	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S201	1	S200 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S202	1	S201 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S203	1	S202 and(intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04

S204	1	S203 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S205	0	S204 and metal adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:05
S206	1	S204 and metal	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:06
S207	0	S206 and bright adj field	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:07
S208	0	S206 and bright	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:07
S209	1	S206 and (UV or DUV)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:08
S210	0	S209 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:08
S211	0	S209 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:09
S212	1	S209 and contrast	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:10

S213	0	S212 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:10
S214	795256	select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:12
S215	2665	S214 and polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:13
S216	12	S215 and bright adj field	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:13
S217	9	S216 and (UV or DUV)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:13
S218	3	S217 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:13
S219	3	S218 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:13
S220	0	S219 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:14
S221	0	S219 and metal adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:14

S222	0	S219 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S223	4	S216 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
S224	0	S223 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
S225	0	S223 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15

6/29/09 2:51:24 PM

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